

# Index

## A

Additive manufacturing, 145, 146, 152, 153  
Aspheric, 87, 91

## C

Coating, 43, 44, 48, 79, 88, 90, 102, 165–168,  
170, 171, 173, 174, 176–178, 180–190

## D

Diamond turning, 5, 87, 91, 92  
Direct laser deposition, 146, 152

## E

Elastic emission machining, 87, 91, 105, 113  
Electrochemical, 9, 16, 21, 22, 25–28, 30–35,  
37, 75, 77, 155, 171, 172, 191  
Etching, 22, 32, 42, 43, 45–49, 60, 61, 66, 68,  
69

## G

Glass, 13, 15, 32, 58, 60, 68, 88, 91, 95, 100,  
168

## I

Ion beam figuring, 87, 91, 99, 113

## L

Laser machining, 13  
Lithography, 2, 13, 35, 78, 83, 87, 88, 90, 99

## M

Magnetic-field, 41, 62, 63, 69, 109, 110  
Magneto-rheological finishing, 87, 91, 109, 113  
MEMS, 2, 56, 73, 88, 137  
Micro-drilling, 3, 7  
Micro-ECM, 2, 9  
Micro-EDM, 9, 11, 12, 156  
Microfluidic, 13  
Micro-injection moulding, 12, 122, 141  
Micro-machining, 1, 2, 13, 17, 30, 34, 37  
Micro-milling, 2, 3, 126, 139  
Micro-turning, 3

## N

Nano-EDM, 71, 74–77, 83  
Nano-grinding, 74  
Nano-machining, 71, 72, 75, 77, 83

## P

Photochemical machining, 41, 42, 45, 48, 56,  
60, 62, 64, 66, 68  
Plasma, 91, 173, 175, 176, 182  
Polishing, 16, 22, 91, 93, 94, 98, 99, 101, 102,  
104, 109, 111, 145, 153–155, 160  
Powder bed fusion, 145, 146, 148, 149

## S

Selective laser melting, 147, 148

## U

Ultrasonic, 15, 31, 35, 41, 64–66, 80, 82